



Final Product Change Notification

201803008F01

Issue Date: 08-Jun-2018

Effective Date: 06-Sep-2018

Here's your personalized quality information concerning products Digi-Key purchased from NXP. For detailed information we invite you to view this notification online



QUALITY

Change Category

- | | | | | |
|----------------------------------------------|---------------------------------------------|----------------------------------------------------|-----------------------------------------|---------------------------------------------------------|
| <input type="checkbox"/> Wafer Fab Process | <input type="checkbox"/> Assembly Process | <input type="checkbox"/> Product Marking | <input type="checkbox"/> Test Location | <input checked="" type="checkbox"/> Design |
| <input type="checkbox"/> Wafer Fab Materials | <input type="checkbox"/> Assembly Materials | <input type="checkbox"/> Mechanical Specification | <input type="checkbox"/> Test Process | <input type="checkbox"/> Errata |
| <input type="checkbox"/> Wafer Fab Location | <input type="checkbox"/> Assembly Location | <input type="checkbox"/> Packing/Shipping/Labeling | <input type="checkbox"/> Test Equipment | <input type="checkbox"/> Electrical spec./Test coverage |
| <input type="checkbox"/> Firmware | <input type="checkbox"/> Other | | | |

LPC802 Change to Revision "1B"

Description of Change

Microcontroller product LPC802 will be sourced from the new product version Rev "1B". Currently released version for the parts LPC802M001JDH16, LPC802M001JDH20 and LPC802M001JHI33 is Rev "0A" and for the parts LPC802M011JDH20 is "1A".

- This change resolves the known functional deviation DPD.1 as documented in the device errata: DPD.1: Port pin PIO0_4 cannot be used to wake up the device from deep power-down mode.
- No wafer fab location or process change.
- Device functionality does not change.

Reason for Change

To resolve known functional deviation DPD.1 as documented in the errata.

Identification of Affected Products

Top side marking

Refer to Remarks section for detail.

Product Availability

Sample Information

Samples are available upon request

Production

Planned first shipment 18-Sep-2018

Anticipated Impact on Form, Fit, Function, Reliability or Quality

Although the new product revision is expected to be electrically identical, it is recommended that customers fully characterize the change in their applications.

Data Sheet Revision

No impact to existing datasheet

Disposition of Old Products

Existing inventory will be shipped until depleted

Timing and Logistics

In compliance with JEDEC J-STD-046, your acknowledgement of this change is expected by 08-Jul-2018.

Remarks

The product version is reflected in the last 2 characters of the last line on the marking:

For the part LPC802M001JDH16, LPC802M001JDH20 and LPC802M001JHI33, the last 2 characters of the last line will be changed from "0A" to "1B".

For the part LPC802M011JDH20, the last 2 characters of the last line will be changed from "1A" to "1B".

For sample availability please contact your local distributor or NXP Sales.

Contact and Support

For all inquiries regarding the ePCN tool application or access issues, please contact NXP "Global Quality Support Team".

For all Quality Notification content inquiries, please contact your local NXP Sales Support team.

For specific questions on this notice or the products affected please contact our specialist directly:

Name Joy Li

Position Product Engineer

e-mail address pengyan.li@nxp.com

At NXP Semiconductors we are constantly striving to improve our product and processes to ensure they reach the highest possible Quality Standards.

Customer Focus, Passion to Win.

NXP Quality Management Team.

About NXP Semiconductors

NXP Semiconductors N.V. (NASDAQ: NXPI) provides High Performance Mixed Signal and Standard Product solutions that leverage its leading RF, Analog, Power Management, Interface, Security and Digital Processing expertise. These innovations are used in a wide range of automotive, identification, wireless infrastructure, lighting, industrial, mobile, consumer and computing applications.

You have received this email because you are a designated contact or subscribed to NXP Quality Notifications. NXP shall not be held liable if this Notification is not correctly distributed within your organization.

This message has been automatically distributed. Please do not reply.

[NXP | Privacy Policy | Terms of Use](#)

NXP Semiconductors

High Tech Campus, 5656 AG Eindhoven, The Netherlands

© 2006-2010 NXP Semiconductors. All rights reserved.

Changed Orderable Part#	Changed Part 12NC	Changed Part Number	Changed Part Description	Package Outline	Package Name	Status	Product Line
LPC802M001JDH16FP	935344357129	LPC802M001JDH16	32-bit ARM Cortex-M0+	SOT403-1	TSSOP16	RFS	BL Microcontrollers
LPC802M001JDH20FP	935344358129	LPC802M001JDH20	32-bit ARM Cortex-M0+	SOT360-1	TSSOP20	RFS	BL Microcontrollers
LPC802M001JHI33E	935345948551	LPC802M001JHI33	32-bit ARM Cortex-M0+	SOT617-11	HVQFN32	RFS	BL Microcontrollers
LPC802M011JDH20FP	935344359129	LPC802M011JDH20	32-bit ARM Cortex-M0+	SOT360-1	TSSOP20	RFS	BL Microcontrollers